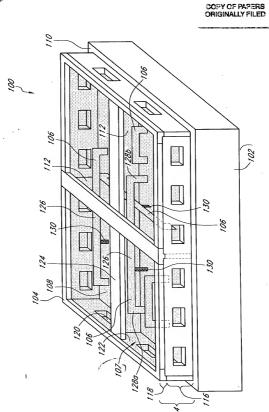
MULTI-CHIP ELECTRONIC PACKAGE AND COOLING SYSTEM Paul A. Farrar et al.

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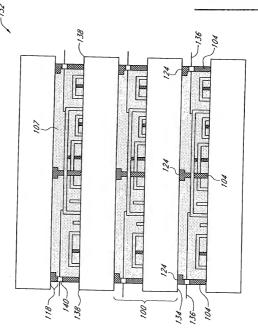


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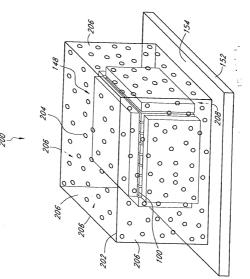
FIG. 2



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